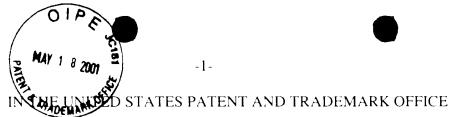
AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): DONAGOWP MASINTYRE				Docket No. MCSP-101	
	8 2001 Hilling Date Examiner D. Willie			Group Art Unit 2814	
Invention: CHIP SCALTE AGES					
TO THE ASSISTANT COMMISSIONER FOR PATENTS:  Transmitted herewith is an amendment in the above-identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
CLAIMS REMAINING AFTER AMENDMENT	HIGHEST #	NUMBER EXTRA  R CLAIMS PRESENT	RATE	ADDITIONAL	
10 -			x \$18	<del> </del>	
3 -	3 =	0	x \$80	.00 \$0.00	
Multiple Dependent Claims (check if applicable)  \$0.00					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT				\$0.00	
<ul> <li>No additional fee is required for amendment.</li> <li>Please charge Deposit Account No. in the amount of         A duplicate copy of this sheet is enclosed.</li> <li>A check in the amount of to cover the filing fee is enclosed.</li> <li>The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-1703         A duplicate copy of this sheet is enclosed.</li> <li>Any additional filing fees required under 37 C.F.R. 1.16.</li> <li>Any patent application processing fees under 37 CFR 1.17.</li> <li>Michael J. Pollock</li> <li>Reg. No. 29,098</li> </ul>					
	TO THE A with is an amendment in a calculated and is transical color of the copy of this sheet is earlied or calculated and is required for a charge Deposit Account of the copy of this sheet is earlied or credit any over the copy of this sheet	TO THE ASSISTANT COM with is an amendment in the above-identi n calculated and is transmitted as shown to CLAIMS A  CLAIMS REMAINING HIGHEST #  AFTER AMENDMENT PREV. PAID FOR  10 - 20 = 3 - 3 = ent Claims (check if applicable)  TOTAL ADDITIO  TOTAL ADDITIO  Total amount of to cover the amount of to cover the amissioner is hereby authorized to charge cation or credit any overpayment to Deposit account No.  In the amount of to cover the amissioner is hereby authorized to charge cation or credit any overpayment to Deposit accopy of this sheet is enclosed.  In the amount of to cover the amissioner is hereby authorized to charge cation or credit any overpayment to Deposit accopy of this sheet is enclosed.  In the amount of to cover the amissioner is hereby authorized to charge cation or credit any overpayment to Deposit accopy of this sheet is enclosed.  In the amount of to cover the amissioner is hereby authorized to charge cation or credit any overpayment to Deposit accopy of this sheet is enclosed.  In the amount of to cover the amissioner is hereby authorized to charge cation or credit any overpayment to Deposit accopy of this sheet is enclosed.  In the amount of to cover the amissioner is hereby authorized to charge cation or credit any overpayment to Deposit accopy of this sheet is enclosed.  In the amount of	TO THE ASSISTANT COMMISSIONER FOR PATE with is an amendment in the above-identified application. In calculated and is transmitted as shown below.  CLAIMS AS AMENDED  CLAIMS REMAINING HIGHEST # NUMBER EXTRA AFTER AMENDMENT PREV PAID FOR CLAIMS PRESENT  10 - 20 = 0  3 - 3 = 0  Part Claims (check if applicable)  TOTAL ADDITIONAL FEE FOR THIS AMENGED  TOTAL ADDITIONAL FEE FOR THIS AMENGED  Total amount of the copy of this sheet is enclosed. In the amount o	TO THE ASSISTANT COMMISSIONER FOR PATENTS:  with is an amendment in the above-identified application.  calculated and is transmitted as shown below.  CLAIMS AS AMENDED  CLAIMS REMAINING  AFTER AMENDMENT  10 - 20 = 0 x \$18  3 - 0 x \$80  Int Claims (check if applicable)  TOTAL ADDITIONAL FEE FOR THIS AMENDMENT  To copy of this sheet is enclosed.  In the amount of to cover the filling fee is enclosed.  In the amount of to cover the filling fee is enclosed.  In the amount of the following fees association or credit any overpayment to Deposit Account No. 50-1703  the copy of this sheet is enclosed.  additional filling fees required under 37 C.F.R. 1.16.  patent application processing fees under 37 C.F.R. 1.16.  patent application processing fees under 37 C.F.R. 1.16.  Dated May 16, 2001	

on May 16, 2001 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents. Washington, D.C. 20231

Chianti Appling

na**n.** .

Typed or Printed Name of Person Mailing Correspondence



In re Patent Application of

DONALD M. MACINTYRE

Application No.: 09/045,507

Filed: March 20, 1998

For: CHIP SCALE PACKAGES

Group Art Unit: 2814

Examiner: D. Willie

RESPONSE TO OFFICE ACTION MAILED NOVEMBER 21, 2000

121 Spear Street, Suite 290 San Francisco, CA 94105 (415) 512-1312

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope, addressed to: Commissioner for Patents, Washington, DC 20231 on May 16, 2001

STALLMAN & POLLOCK LLP

Commissioner for Patents Washington, D.C. 20231

Sir:

Please amend the above-identified application as follows:

## IN THE CLAIMS

Please cancel claims 18-38 and add the following new claims:

--39. (New) A semiconductor integrated circuit structure comprising:

a semiconductor wafer substrate that includes a plurality of semiconductor integrated circuit die formed in an upper surface of said wafer substrate:

for each semiconductor integrated circuit die, a plurality of conductive die bond pads formed on an upper surface of said integrated circuit die:

a glass sheet having a plurality of holes formed therethrough from an upper surface of the but the American well as of the above shout